

Enroute
2-26-02
2/26/02
PR5
PNOT
SA
EL 844051657

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/148,723
Priority Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 3729
Priority Examiner A. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

PRELIMINARY AMENDMENT

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.
(Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3817

Sir:

This is a preliminary amendment accompanying a Request for Continuation Application for the above-entitled patent application. Prior to examining the application, please enter the following amendments.

AMENDMENTS